

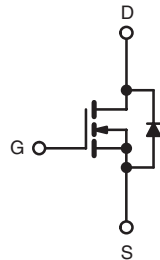
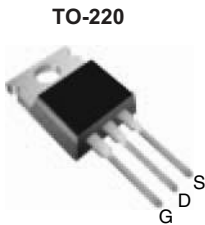


**THE DATASHEET OF
IRFB11N50A**



Power MOSFET

| PRODUCT SUMMARY | | |
|---------------------------|-----------------|------|
| V_{DS} (V) | 500 | |
| $R_{DS(on)}$ (Ω) | $V_{GS} = 10$ V | 0.52 |
| Q_g (Max.) (nC) | 52 | |
| Q_{gs} (nC) | 13 | |
| Q_{gd} (nC) | 18 | |
| Configuration | Single | |



N-Channel MOSFET

FEATURES

- Low Gate Charge Q_g Results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and current
- Lead (Pb)-free Available



Available
RoHS*
COMPLIANT

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching

APPLICABLE OFF LINE SMPS TOPOLOGIES

- Two Transistor Forward
- Half and Full Bridge
- Power Factor Correction Boost

| ORDERING INFORMATION | |
|----------------------|----------------|
| Package | TO-220 |
| Lead (Pb)-free | IRFB11N50APbF |
| | SiHFB11N50A-E3 |
| SnPb | IRFB11N50A |
| | SiHFB11N50A |


| ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted | | | | |
|--|------------------|------------------|-------|----------|
| PARAMETER | SYMBOL | LIMIT | UNIT | |
| Drain-Source Voltage | V_{DS} | 500 | V | |
| Gate-Source Voltage | V_{GS} | ± 30 | | |
| Continuous Drain Current | V_{GS} at 10 V | $T_C = 25$ °C | 11 | A |
| | | $T_C = 100$ °C | 7.0 | |
| Pulsed Drain Current ^a | I_{DM} | 44 | | |
| Linear Derating Factor | | 1.3 | W/°C | |
| Single Pulse Avalanche Energy ^b | E_{AS} | 275 | mJ | |
| Repetitive Avalanche Current ^a | I_{AR} | 11 | A | |
| Repetitive Avalanche Energy ^a | E_{AR} | 17 | mJ | |
| Maximum Power Dissipation | $T_C = 25$ °C | P_D | 170 | W |
| Peak Diode Recovery dV/dt^c | dV/dt | 6.9 | V/ns | |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | - 55 to + 150 | °C | |
| Soldering Recommendations (Peak Temperature) | for 10 s | 300 ^d | | |
| Mounting Torque | 6-32 or M3 screw | 10 | | lbf · in |
| | | 1.1 | N · m | |

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Starting $T_J = 25$ °C, $L = 4.5$ mH, $R_G = 25$ Ω , $I_{AS} = 11$ A (see fig. 12).
- $I_{SD} \leq 11$ A, $dI/dt \leq 140$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 150$ °C.
- 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

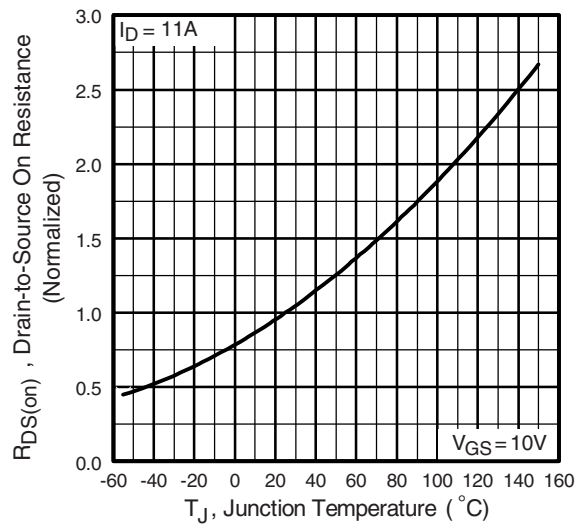
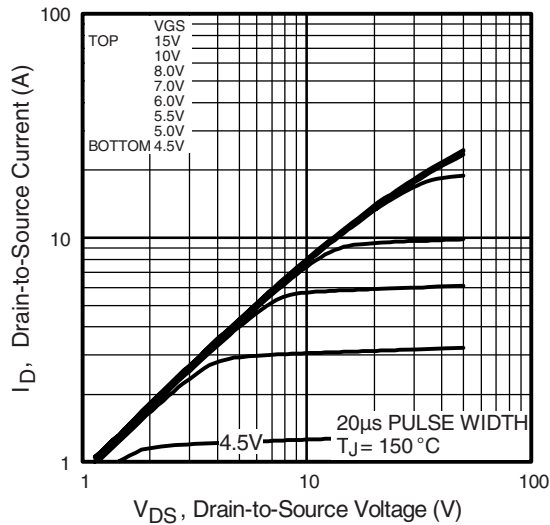
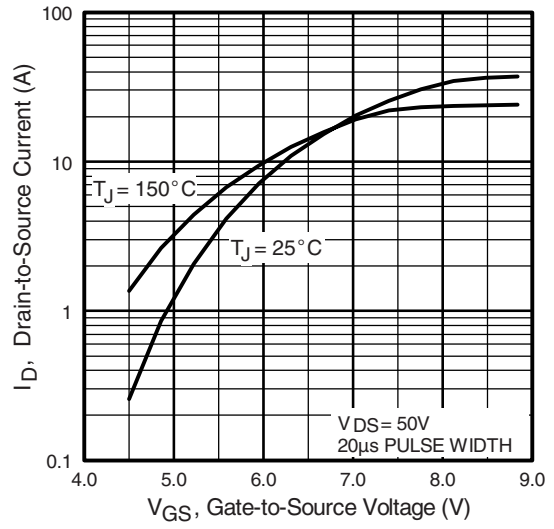
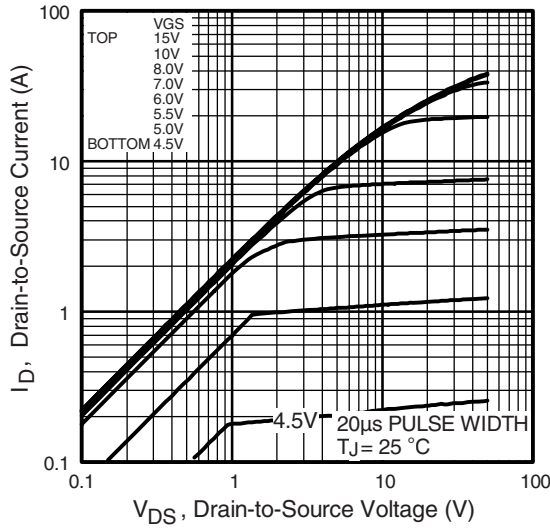
| THERMAL RESISTANCE | | | | |
|-------------------------------------|------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient | R_{thJA} | - | 62 | °C/W |
| Case-to-Sink, Flat, Greased Surface | R_{thCS} | 0.50 | - | |
| Maximum Junction-to-Case (Drain) | R_{thJC} | - | 0.75 | |

| SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted | | | | | | | |
|--|-----------------------|--|--|------|-----------|---------------|----|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT | |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | 500 | - | - | V | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | 2.0 | - | 4.0 | V | |
| Gate-Source Leakage | I_{GSS} | $V_{GS} = \pm 30\text{ V}$ | - | - | ± 100 | nA | |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$ | - | - | 25 | μA | |
| | | $V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$ | - | - | 250 | | |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}, I_D = 6.6\text{ A}^b$ | - | - | 0.52 | Ω | |
| Forward Transconductance | g_{fs} | $V_{DS} = 50\text{ V}, I_D = 6.6\text{ A}$ | 6.1 | - | - | S | |
| Dynamic | | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0\text{ V},$ $V_{DS} = 25\text{ V},$ $f = 1.0\text{ MHz},$ see fig. 5 | - | 1423 | - | pF | |
| Output Capacitance | C_{oss} | | - | 208 | - | | |
| Reverse Transfer Capacitance | C_{riss} | | - | 8.1 | - | | |
| Output Capacitance | C_{oss} | $V_{GS} = 0\text{ V}$ | $V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$ | - | 2000 | - | |
| Effective Output Capacitance | $C_{oss\text{ eff.}}$ | | $V_{DS} = 400\text{ V}, f = 1.0\text{ MHz}$ | - | 55 | - | |
| Total Gate Charge | Q_g | $V_{GS} = 10\text{ V}$ | $I_D = 11\text{ A}, V_{DS} = 400\text{ V}$ see fig. 6 and 13 ^b | - | - | 52 | nC |
| Gate-Source Charge | Q_{gs} | | | - | - | 13 | |
| Gate-Drain Charge | Q_{gd} | | | - | - | 18 | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 250\text{ V}, I_D = 11\text{ A}$ $R_G = 9.1\text{ }\Omega, R_D = 22\text{ }\Omega,$ see fig. 10 ^b | - | 14 | - | ns | |
| Rise Time | t_r | | - | 35 | - | | |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 32 | - | | |
| Fall Time | t_f | | - | 28 | - | | |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous Source-Drain Diode Current | I_S | MOSFET symbol showing the integral reverse p - n junction diode  | - | - | 11 | A | |
| Pulsed Diode Forward Current ^a | I_{SM} | | - | - | 44 | | |
| Body Diode Voltage | V_{SD} | $T_J = 25\text{ }^\circ\text{C}, I_S = 11\text{ A}, V_{GS} = 0\text{ V}^b$ | - | - | 1.5 | V | |
| Body Diode Reverse Recovery Time | t_{rr} | $T_J = 25\text{ }^\circ\text{C}, I_F = 11\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$ | - | 510 | 770 | ns | |
| Body Diode Reverse Recovery Charge | Q_{rr} | | - | 3.4 | 5.1 | μC | |
| Forward Turn-On Time | t_{on} | Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D) | | | | | |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.
- c. $C_{oss\text{ effective}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80 % V_{DS} .

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



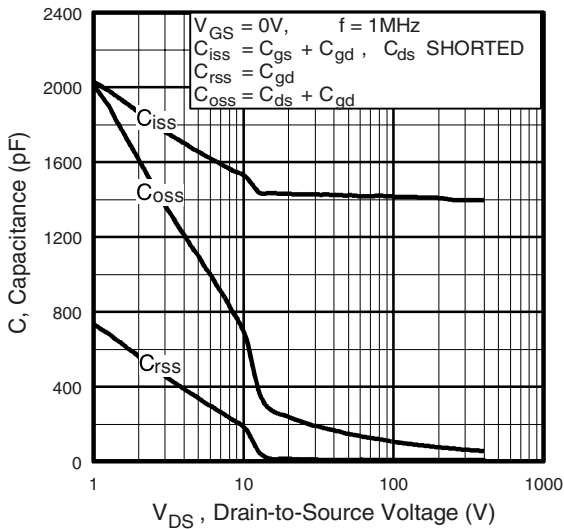


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

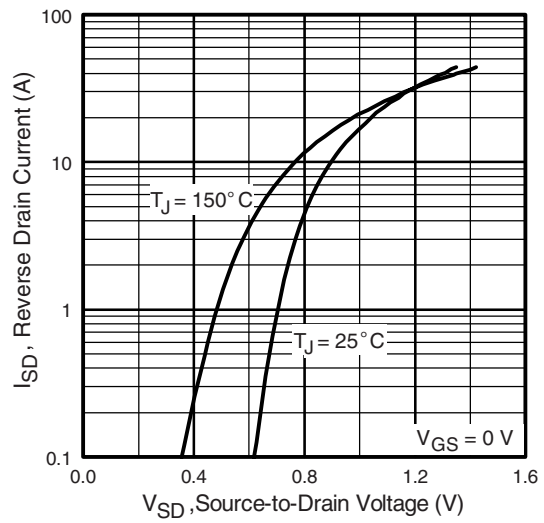


Fig. 7 - Typical Source-Drain Diode Forward Voltage

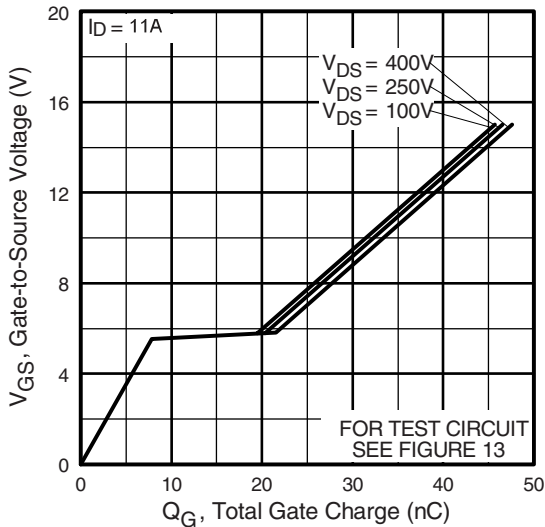


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

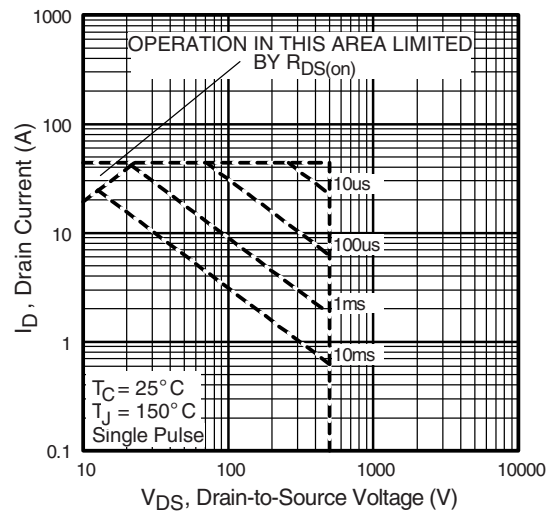


Fig. 8 - Maximum Safe Operating Area

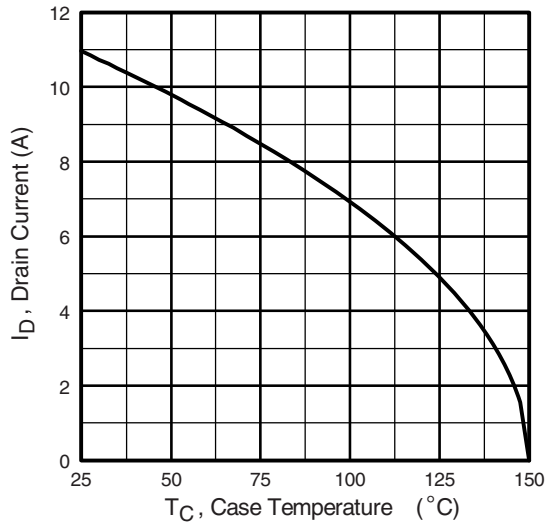


Fig. 9 - Maximum Drain Current vs. Case Temperature

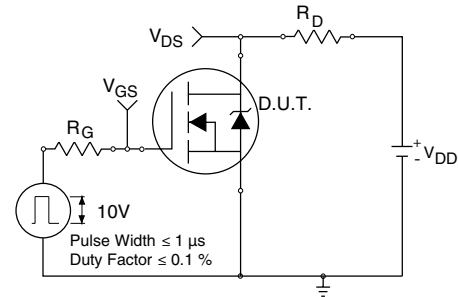


Fig. 10a - Switching Time Test Circuit

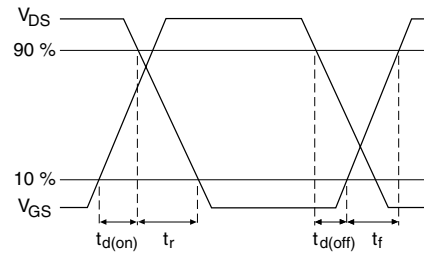


Fig. 10b - Switching Time Waveforms

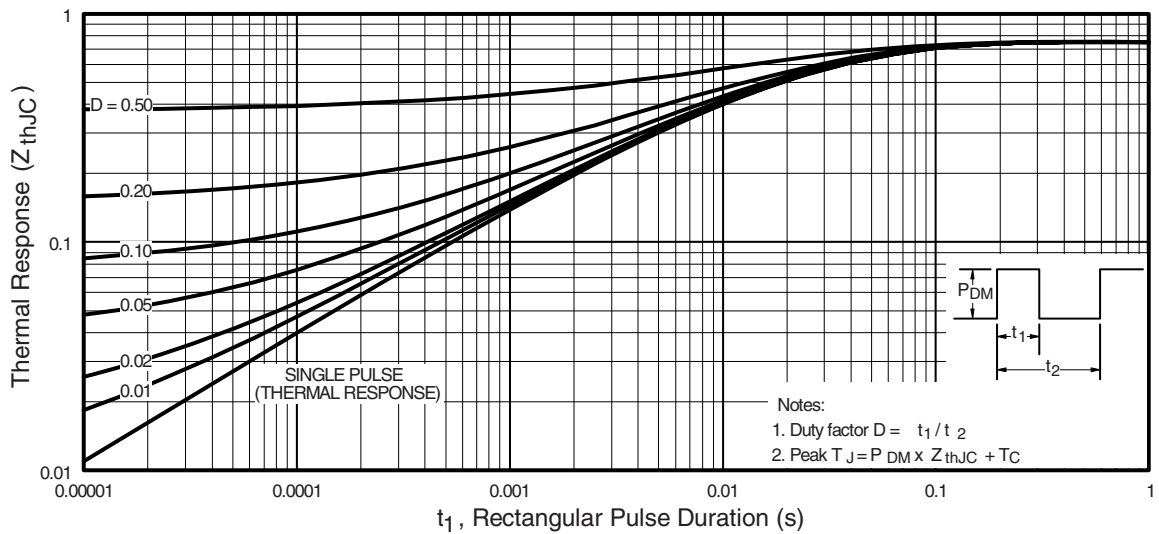


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

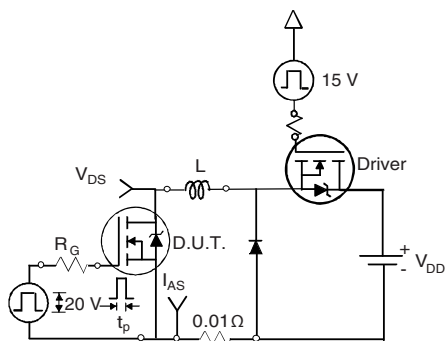


Fig. 12a - Unclamped Inductive Test Circuit

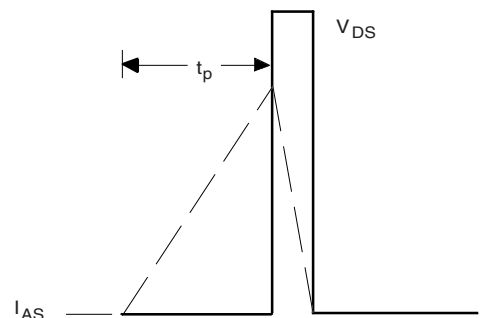


Fig. 12b - Unclamped Inductive Waveforms

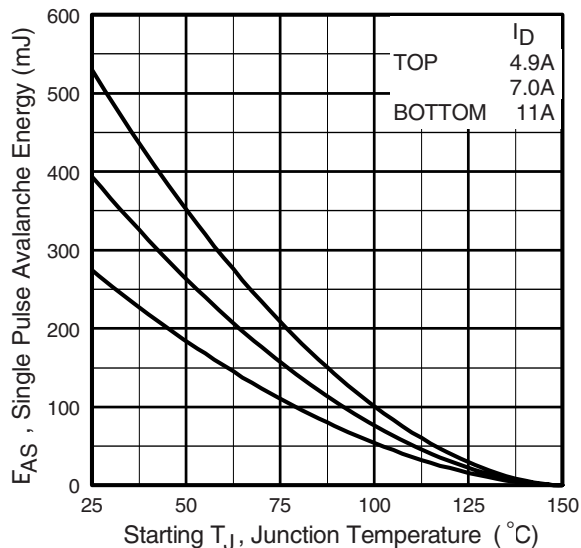


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

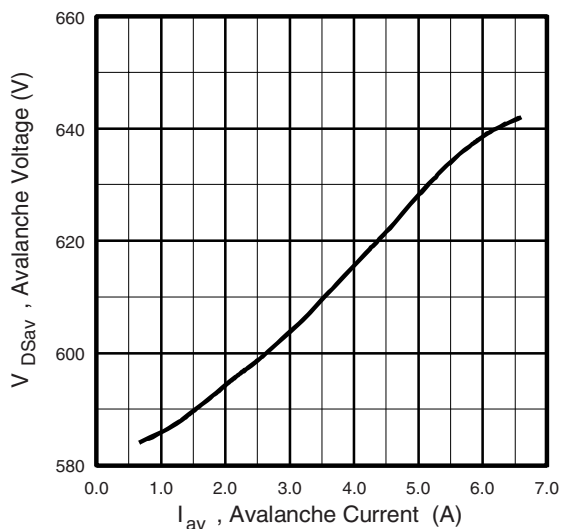


Fig. 12d - Typical Drain-to-Source Voltage vs. Avalanche Current

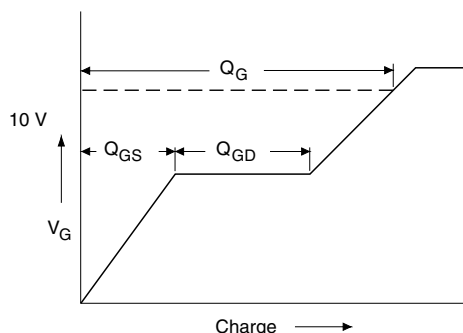


Fig. 13a - Basic Gate Charge Waveform

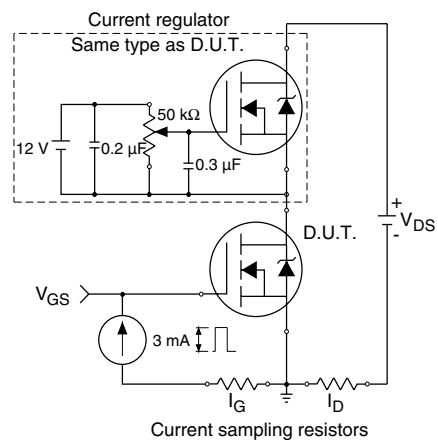
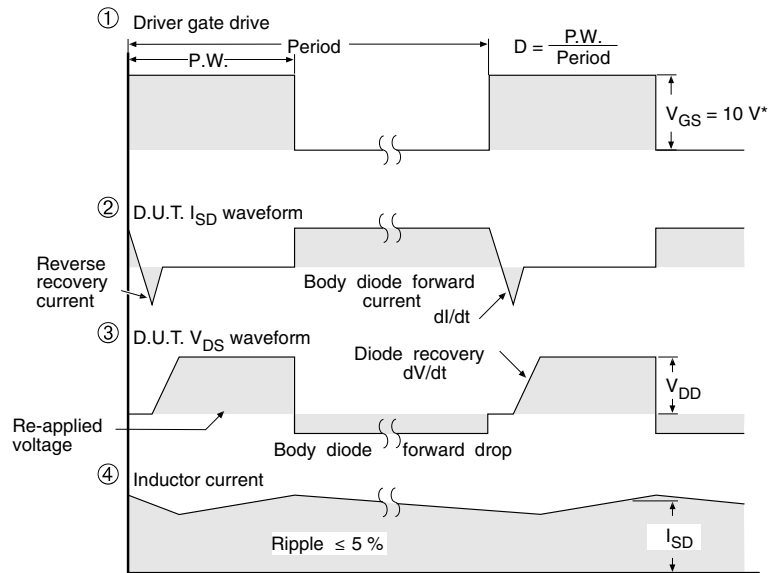
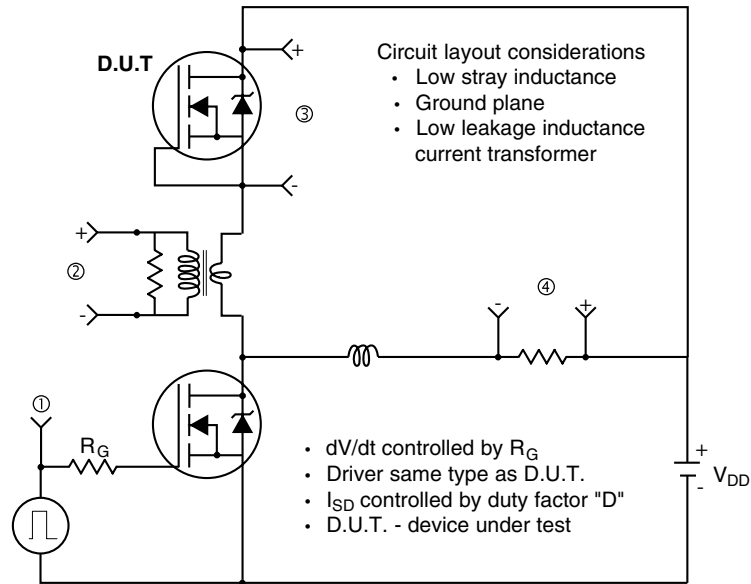


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



* $V_{GS} = 5\text{ V}$ for logic level devices

Fig. 14 - For N-Channel

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